

ABSTRACT OF THE DISCLOSURE

5 A stacked package of semiconductor packaging units includes a direct
electrical connection between leads of an upper semiconductor package unit,
and includes direct electrical connections between selected leads of the upper
semiconductor package unit and a lower semiconductor package unit. Leads
10 of the upper semiconductor package unit are straightened, and chip-select
and clock-enable leads are shortened and electrically connected to adjacent
not-connected leads. Selected leads of the upper semiconductor package
unit are electrically connected directly to underlying leads of the lower
semiconductor packaging unit. Electrical connections preferably are solder
15 connections.

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